"Circuits and Systems for Sustainable Development"
ISCAS 2024
Singapore | May 19-22, 2024
Resorts World Sentosa Convention Centre

Call for Papers

The IEEE International Symposium on Circuits and Systems (ISCAS) is the flagship conference of the IEEE Circuits and Systems Society and the world's premier forum for researchers in the active fields of theory, design and implementation of circuits and systems. ISCAS 2024 will be held in Singapore, from May 19 to 22, 2024. ISCAS 2024 is inspired by the theme **"Circuits and Systems for Sustainable Development"**, which is perfectly aligned with the host city Singapore's goal. This symposium will include technical oral lectures and poster sessions, special sessions, tutorials, live demonstrations and workshops, ranging from various topics in circuits and systems.

To implement the above vision, this year's conference will highlight the following innovation themes:

- *Artificial Intelligence and Deep Learning*
- *Smart Systems for Automotive*
- *Brain: Innovation Neurotechnologies*
- *Intelligent Cyber Security Systems*
- *Food Security and Climate Change*
- *Ultra Low Power Circuits and Systems*

Collecting contributions in areas of Circuits and Systems, including but not limited to:

- Analog and Mixed Signal Circuits and Systems
- Digital Integrated Circuits and Systems
- Power and Energy Circuits and Systems
- Sensory Circuits and Systems
- Nonlinear Systems and Circuit Theory
- Digital Signal Processing
- Multimedia Systems and Applications

- Communications Circuits and Systems
- Biomedical Circuits and Systems
- Neural Networks and Neuromorphic Engineering
- Beyond CMOS: Nanoelectronics and Heterogeneous System Integration
- Education in Circuits and Systems
- Electronic Design Automation

Special Initiatives of ISCAS 2024:

- **Emerging Technologies Workshops**
  On *Information Security*, *Climate Change*, and *GeronCAS*.
- **Cross-Society Special Sessions**
  Co-organized by CASS and other IEEE societies/councils, on recent attractive themes for cross-disciplinary collaboration.
- **Special Sections in IEEE Transactions**
  Selected papers will be invited for possible publications in: IEEE Trans. on Circuits and Systems – Part I, IEEE Trans. on Circuits and Systems – Part II, and IEEE Trans. on Biomedical Circuits and Systems.

Important Dates:

Special Sessions Proposal:	Sep 17, 2023
Special Sessions Proposal Notification:	Oct 1, 2023
Special Session Papers Submission:	Oct 15, 2023
Regular Papers Submission:	Oct 15, 2023
Tutorials Proposal:	Oct 15, 2023
Live Demos Submission:	Oct 15, 2023
All Authors' Decision Notification:	Jan 15, 2024

2024.ieee-iscas.org

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